

Panasonic

ideas for life

高热伝導性ガラスコンポジット基板材料
High Thermal Conductive Glass composite Circuit Board Materials
高热传导性玻璃复合基板材料

EcooL



より「使いやすい」
Easier to process
更“容易使用”

設計の自由度アップ
加工性は一般FR-4と同等
Enhancing the flexibility for circuit
design, equivalent processability
to conventional FR-4
提高设计自由度

樹脂基板ならではの加工・設計のしやすさと優れたコストパフォーマンスを実現

Inorganic resin circuit boards which realize an excellent processability and a design flexibility as well as an excellent cost performance
加工、設計的简单化以及优异的成本效率



より「安全に」
Safer to use
更“安全”

業界最高水準の耐トラッキング性能 (CTI600)
Industry's highest level of tracking resistance (CTI600)
耐漏電痕性

耐CAF性に優れる
Excellent CAF resistance
耐CAF性优异



より「環境にやさしく」
Environmentally-friendly
更“有益于环境”

ハロゲンフリー
Halogen-free
无卤素

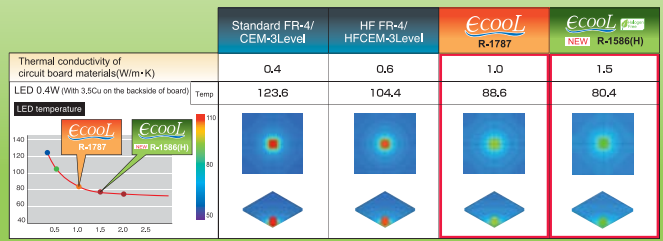
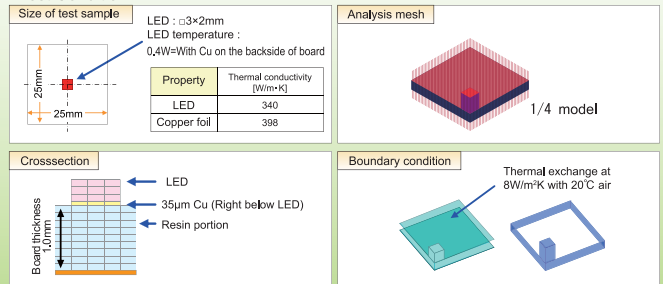


LED Thermal simulation

●Analysis

- To analyze the impact of material thermal conductivity to LEDs raising of temperature by using thermic fluid analysis soft "STAR-CD"
- Assumed heat generation : 0.4W
- Sample board thickness : 1.0mm

●Test Condition



Characteristics

Item	unit	1.5 w/mk EcooL NEW Reference Product	1.0 w/mk EcooL R-1787	R-1786 Conventional CEM-3
Thermal conductivity	W/m·K	1.50	1.10	0.50
Tracking resistance IEC method	-	600 \leq	600 \leq	600 \leq
Dielectric breakdown perpendicular to Lamination	KV/mm	41	43	49
Insulation resistance	M Ω	5x10 ⁸	1x10 ⁸	5x10 ⁸
Dielectric constance (1MHz)	-	5.2	5.1	4.5
Dielectric Dissipation (1MHz)	-	0.020	0.016	0.015
Heat resistance (35 μ m)	°C	220 \uparrow	220 \uparrow	220 \uparrow
Solder heat resistance (260°C)	sec	60 \uparrow	60 \uparrow	60 \uparrow
Tg (TMA)	°C	145	140	140

* The above data are our actual values and not assured values.